TLP283,TLP283-4

TENTATIVE TOSHIBA PHOTOCOUPLER GaAs IRED & PHOTO-TRANSISTOR

TLP283,TLP283-4

PROGRAMMABLE CONTROLLERS AC adapters for PDAs/ on-board power supplies I/O interface boards

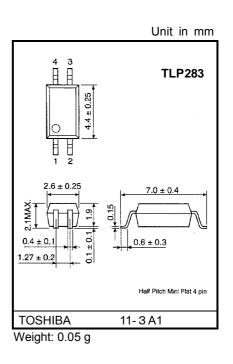
TLP283 and TLP283-4 is a very small and thin coupler, suitable for surface mount assembly in applications such as on-board power supplies, programmable controllers.

TLP283 and TLP283-4 consist of photo transistor, optically coupled to a gallium arsenide infrared emitting diode.

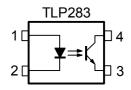
• Collector-Emitter Voltage : 100 V (MIN)

TOSHIBA

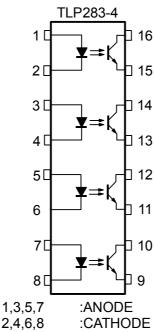
- Current Transfer Ratio : 100% (MIN)@IF=1mA
- 1 Pulse delay time(Note 1) : 100us(MAX)@IF=1mA,RL=10kΩ
- Isolation Voltage : 2500 Vrms (MIN)
- UL Recognized : UL1577, File No. E67349
 Note 1 : 1 Pulse delay time = tON+tOFF



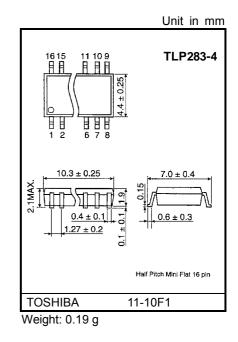
PIN CONFIGURATION(Top view)



1:ANODE 2:CATHODE 3:EMITTER 4:COLLECTOR



9,11,13,15 :EMITTER 10,12,14,16 :COLLECTOR



MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC			RAT			
	CHARACTERISTIC	SYMBOL	TLP283	TLP283-4	UNIT	
	Forward Current	١ _F	50		mA	
	Forward Current Derating	∆I _F /°C	−0.7 (Ta≥53°C)	−0.5 (Ta≥25°C)	mA /°C	
LED	Pulse Forward Current	I _{FP}	1		А	
	Reverse Voltage	V _R	5		V	
	Junction Temperature	Тj	125		°C	
	Collector-Emitter Voltage	V _{CEO}	100		V	
	Emitter-Collector Voltage	V _{ECO}	7		V	
OR	Collector Current	Ι _C	50		mA	
DETECTOR	Collector Power Dissipation (1 Circuit)	P _C	150	100	mW	
D	Collector Power Dissipation Derating(Ta≥25°C) (1 Circuit)	∆P _C /°C	-1.5	-1.0	mW /°C	
	Junction Temperature	Тj	125		°C	
Оре	erating Temperature Range	T _{opr}	-55-	°C		
Storage Temperature Range		T _{stg}	-55-	°C		
Lead Soldering Temperature		T _{sol}	260 (10s)		°C	
Total Package Power Dissipation (1 Circuit)		PT	200	170	mW	
Total Package Power Dissipation Derating (Ta≥25°C) (1 Circuit)		∆P _T /°C	-2.0	-1.7	mW /°C	
Isolation Voltage (Note2)		BVS	2500(AC,1min,R.H.≤60%)		Vrms	

(Note2)Device considered a two terminal device : LED side pins shorted together and DETECTOR side pins shorted together.

INDIVIDUAL ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
LED	Forward Voltage	V _F	I _F = 10 mA	1.0	1.15	1.3	V
	Reverse Current	I _R	V _R = 5 V	_	_	10	μA
	Capacitance	CT	V = 0, f = 1 MHz	_	30	_	pF
DETECTOR	Collector-Emitter Breakdown Voltage	V _(BR) CEO	I _C = 0.5 mA	100	_	_	V
	Emitter-Collector Breakdown Voltage	V _(BR) ECO	I _E = 0.1 mA	7	_	_	V
	Collector Dark Current (Note3)	1050	V _{CE} = 48 V, Ambient Light Below (100 <i>t</i> x)		0.01 (2)	0.1 (10)	μA
		ICEO	V _{CE} = 48 V, Ta = 85°C Ambient Light Below (100 ℓx)	_	2 (4)	50 (50)	μA
	Capacitance (Collector to Emitter)	C _{CE}	V = 0, f = 1 MHz	_	10	_	pF

(Note3) Because of the construction,leak current might be increased by ambient light. Please use photocoupler with less ambient light.

COUPLED ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Current Transfer Ratio	I _C / I _F	I _F = 1 mA, V _{CE} = 5 V	100	_	400	%
Saturated CTR	I _C / I _{F (sat)}	IF = 1 mA, VCE = 0.4 V	50	_	_	%
Collector-Emitter Saturation Voltage	V _{CE (sat)}	I _C = 0.2 mA, I _F = 1 mA	_	0.2	0.4	v
Off-State Collector Current	I _{C (off)}	V _F = 0.7 V, V _{CE} = 48 V		_	10	μA

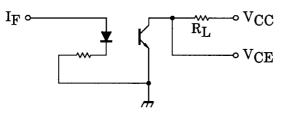
ISOLATION CHARACTERISTICS (Ta = 25°C)

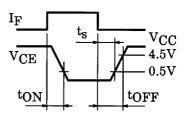
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Capacitance (Input to Output)	CS	V _S = 0 V, f = 1 MHz	_	0.8	_	pF
Isolation Resistance	R _S	V _S = 500 V, R.H.≤60%	5×10 ¹⁰	10 ¹⁴		Ω
	BVS	AC , 1 minute	2500	_	_	Vrms
Isolation Voltage		AC , 1 second,in OIL	_	5000	_	
		DC, 1 minute, in OIL	_	5000	_	Vdc

SWITCHING CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Turn-On Time	t _{ON}	V _{CC} = 5 V, IF = 1 mA R _I = 10kΩ	_	7.5	20	
Turn-Off Time	tOFF		_	70	90	μs
1 Pulse delay time	t _{ON+} t _{OFF}	-		80	100	

(Fig.1)SWITCHING TIME TEST CIRCUIT





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